



## General Description

AFC5521, N & P Pair enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge. These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

## Features

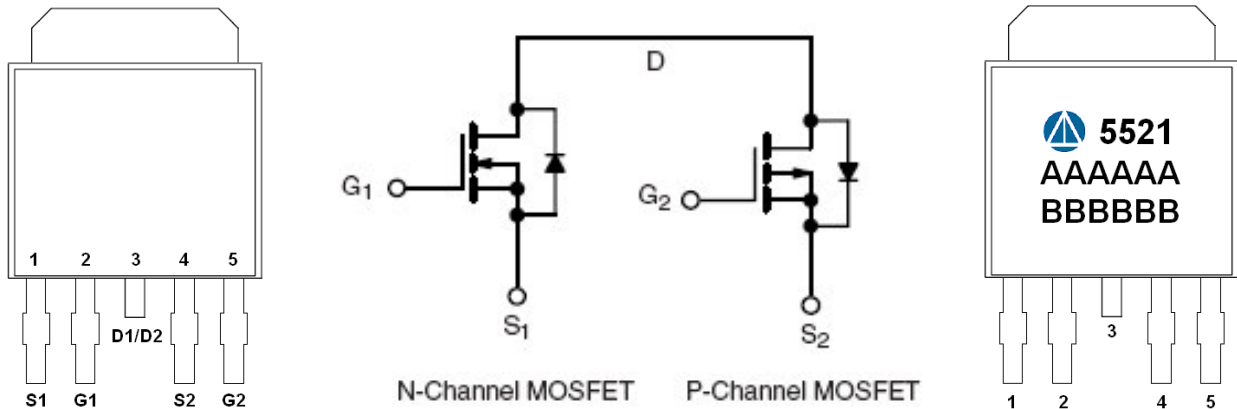
### N-Channel

- 100V/5.0A,  $R_{DS(ON)} = 110m\Omega @ V_{GS} = 10V$
- 100V/3.0A,  $R_{DS(ON)} = 120m\Omega @ V_{GS} = 4.5V$

### P-Channel

- -100V/-5.0A,  $R_{DS(ON)} = 190m\Omega @ V_{GS} = -10V$
- -100V/-3.0A,  $R_{DS(ON)} = 200m\Omega @ V_{GS} = -4.5V$

## Pin Description ( TO-252-4L )



## Application

- DC/DC Conversion
- Load Switch
- DC FAN

## Pin Define

Pin	Symbol	Description
1	S1	Source 1
2	G1	Gate 1
3	D1 / D2	Drain 1 / Drain 2
4	S2	Source 2
5	G2	Gate 2

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFC5521T254RG	5521	TO-252-4L	Tape & Reel	2500 EA

- ※ A Lot code
- ※ B Date code
- ※ AFC5521T254RG : 13" Tape & Reel ; Pb- Free ; Halogen- Free



**Absolute Maximum Ratings ( N-Channel )**

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V <sub>DSS</sub>	100	V
Gate –Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current(T <sub>J</sub> =150°C)	I <sub>D</sub>	T <sub>c</sub> =25°C	5
		T <sub>c</sub> =70°C	3
Pulsed Drain Current	I <sub>DM</sub>	8	A
Continuous Source Current(Diode Conduction)	I <sub>S</sub>	2	
Power Dissipation	P <sub>D</sub>	T <sub>A</sub> =25°C	2.8
		T <sub>A</sub> =70°C	1.8
Operating Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	62.5	°C/W

**Electrical Characteristics ( N-Channel )**

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	100			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1.0	1.8	2.5	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V			1	uA
		V <sub>DS</sub> =80V, V <sub>GS</sub> =0V T <sub>J</sub> =85°C			5	
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 5V, V <sub>GS</sub> =10V	8			A
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.0A		86	110	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =3.0A		90	120	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =3A		12		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =3A, V <sub>GS</sub> =0V		0.8	1.2	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V I <sub>D</sub> ≅4.5A		10	15	nC
Gate-Source Charge	Q <sub>gs</sub>			1.7		
Gate-Drain Charge	Q <sub>gd</sub>			2		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V f=1MHz		415		pF
Output Capacitance	C <sub>oss</sub>			40		
Reverse Transfer Capacitance	C <sub>rss</sub>			20		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =50V, R <sub>L</sub> =23.8Ω I <sub>D</sub> ≅2.1A, V <sub>GEN</sub> =10V R <sub>G</sub> =1.0Ω		10	15	ns
	t <sub>r</sub>			10	15	
Turn-Off Time	t <sub>d(off)</sub>			12	20	
	t <sub>f</sub>			10	15	



**Absolute Maximum Ratings ( P-Channel )**

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V <sub>DSS</sub>	-100	V
Gate –Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current(T <sub>J</sub> =150°C)	I <sub>D</sub>	T <sub>A</sub> =25°C	-5
		T <sub>A</sub> =70°C	-3
Pulsed Drain Current	I <sub>DM</sub>	-8	A
Continuous Source-Drain Diode Current	I <sub>S</sub>	-2	
Power Dissipation	P <sub>D</sub>	T <sub>A</sub> =25°C	2.8
		T <sub>A</sub> =70°C	1.8
Operating Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	62.5	°C/W

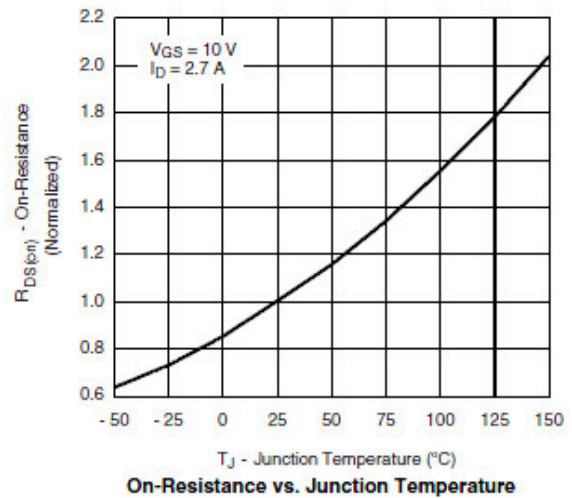
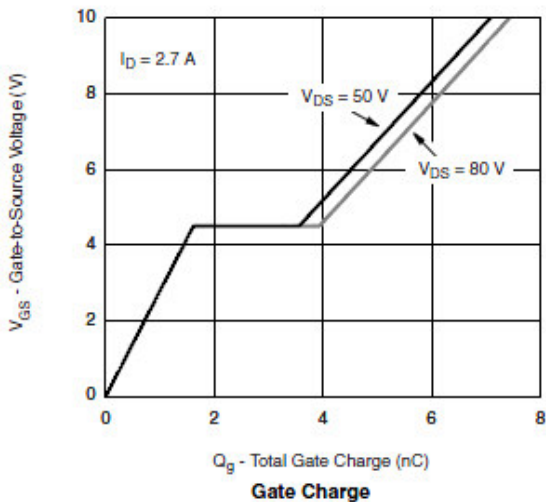
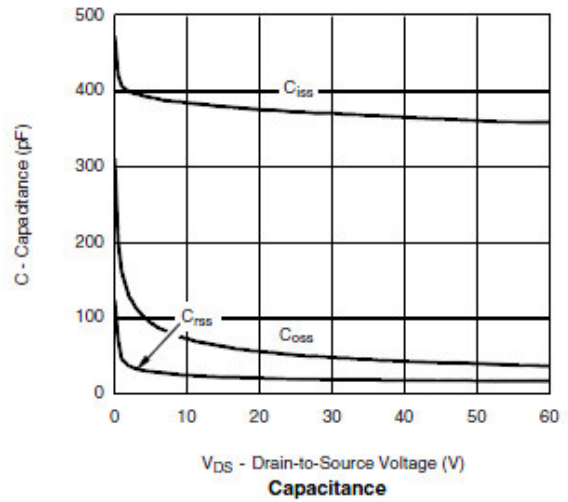
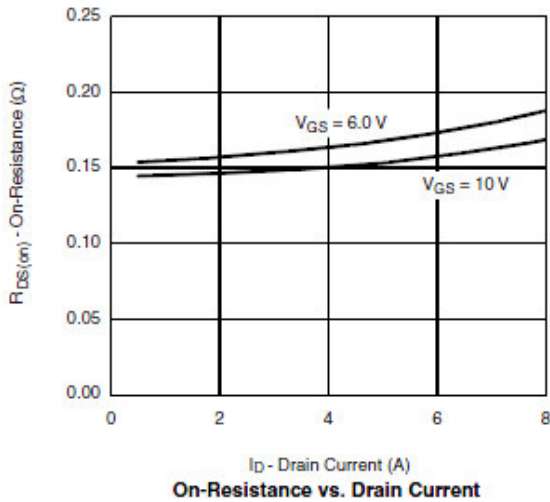
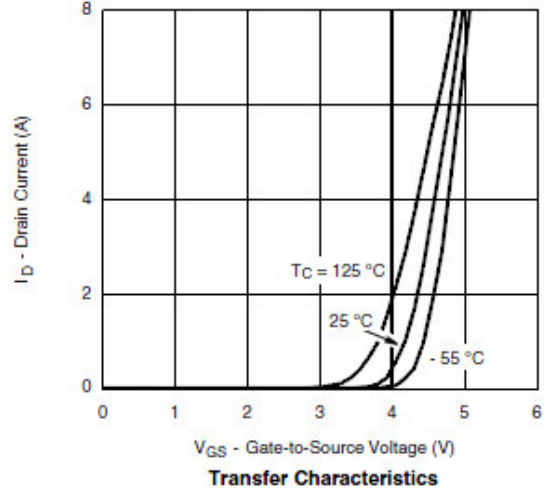
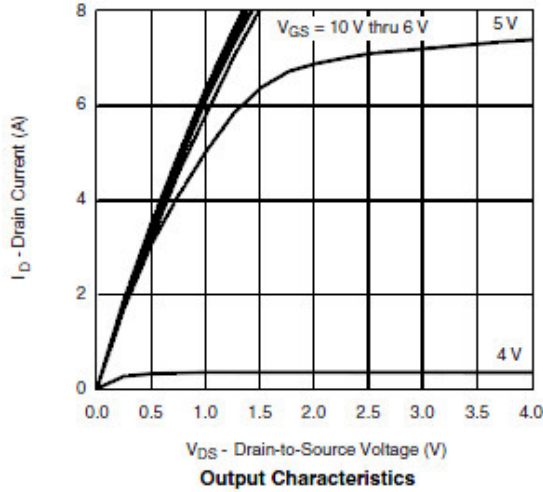
**Electrical Characteristics ( P-Channel )**

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> = -250uA	-100			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = -250uA	-1.0		-2.5	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -80V, V <sub>GS</sub> =0V			-1	
		V <sub>DS</sub> = -80V, V <sub>GS</sub> =0V T <sub>J</sub> =85°C			-30	uA
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ -10V, V <sub>GS</sub> = -10V	-18			A
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> =-5.0A		167	190	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> =-3.0A		177	200	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = -15V, I <sub>D</sub> = -3.2A		12		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = -2A, V <sub>GS</sub> =0V		-0.8	-1.3	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-50V, V <sub>GS</sub> =-4.5V I <sub>D</sub> = -4.0A		12	20	nC
Gate-Source Charge	Q <sub>gs</sub>			3.0		
Gate-Drain Charge	Q <sub>gd</sub>			4.5		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-50V, V <sub>GS</sub> =0V f=1MHz		1100		pF
Output Capacitance	C <sub>oss</sub>			70		
Reverse Transfer Capacitance	C <sub>rss</sub>			45		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-50V, R <sub>L</sub> =17Ω I <sub>D</sub> ≡ -2.8A, V <sub>GEN</sub> =-10V R <sub>G</sub> =1Ω		8	15	ns
	t <sub>r</sub>			15	20	
Turn-Off Time	t <sub>d(off)</sub>			35	50	
	t <sub>f</sub>			10	25	

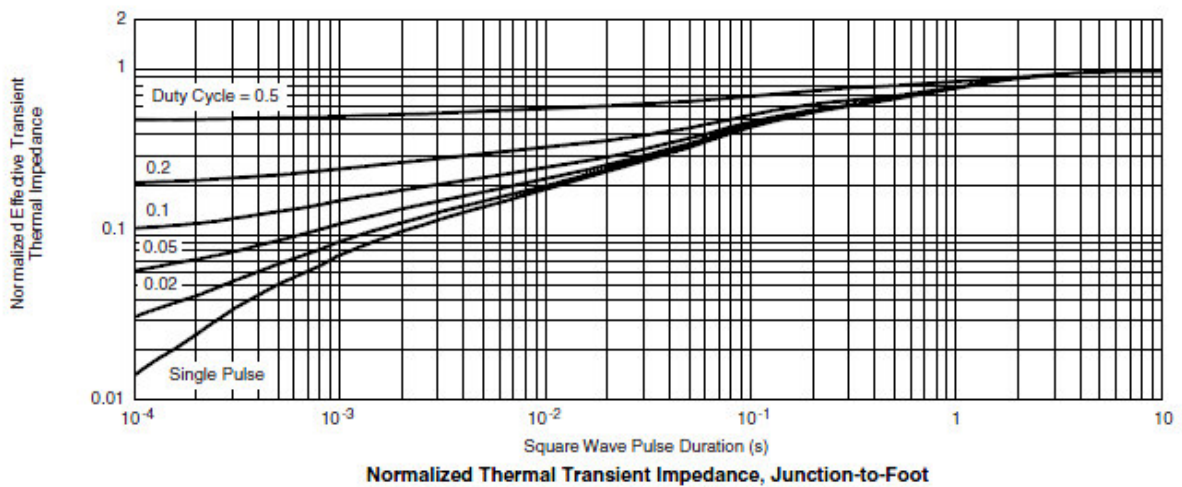
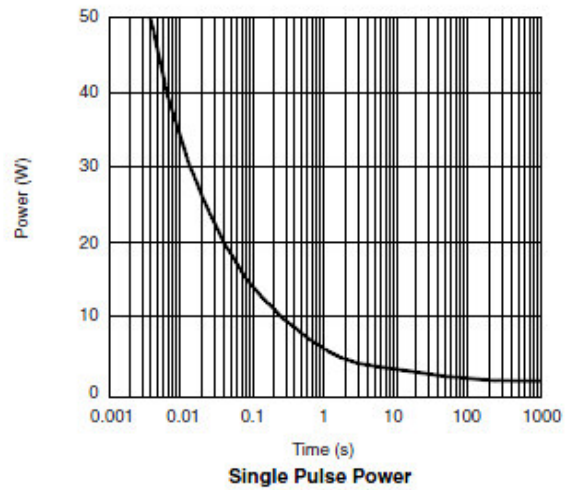
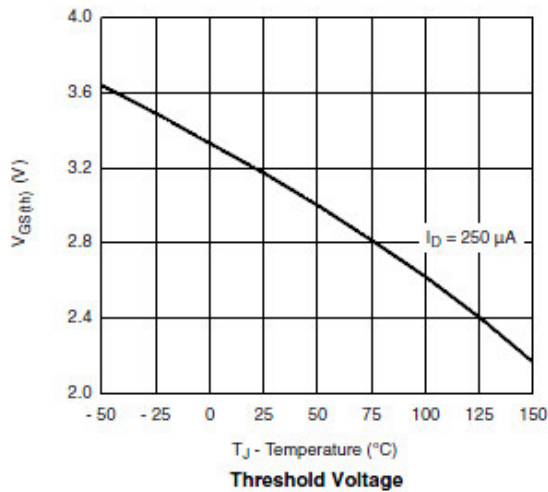
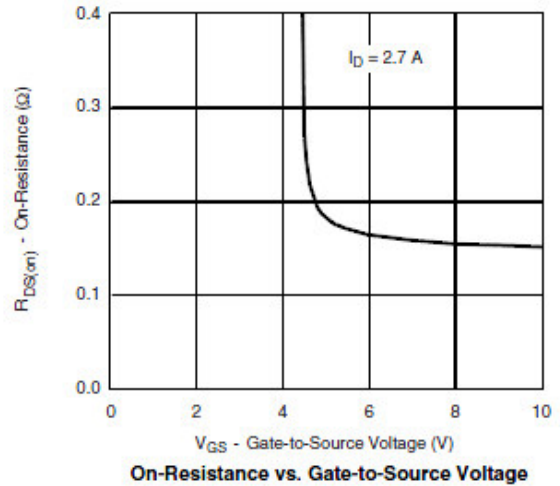
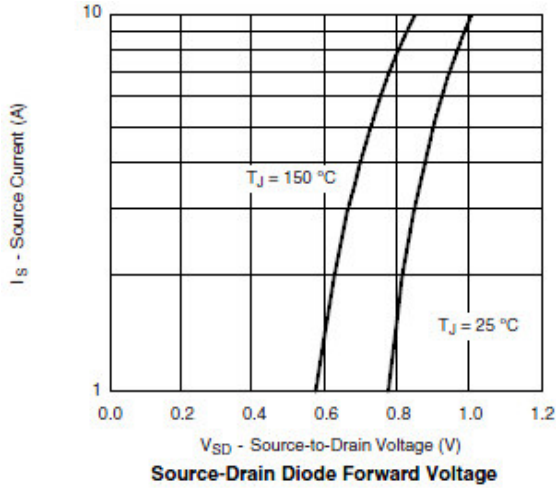


## Typical Characteristics ( N-Channel )



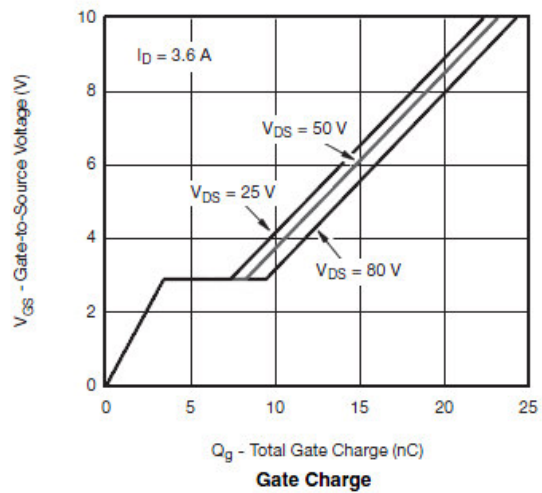
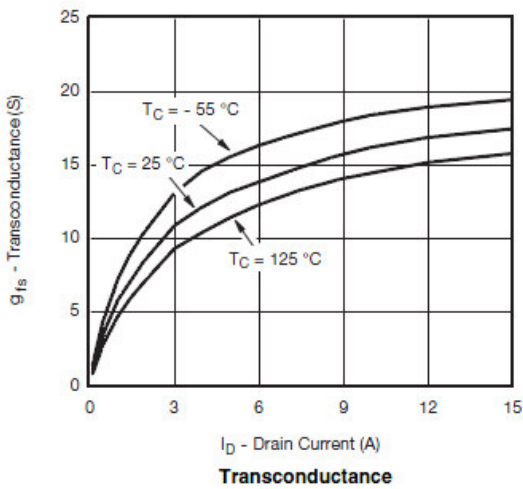
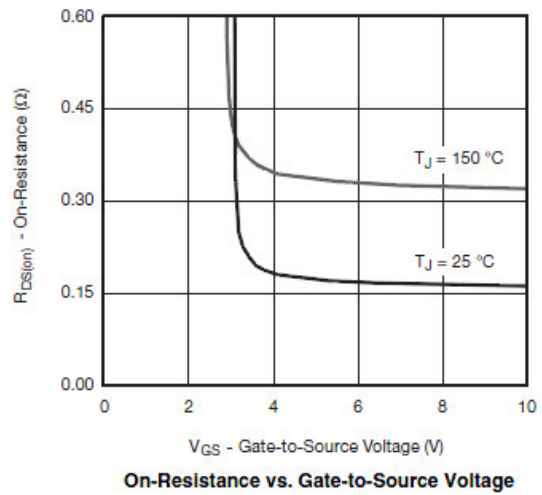
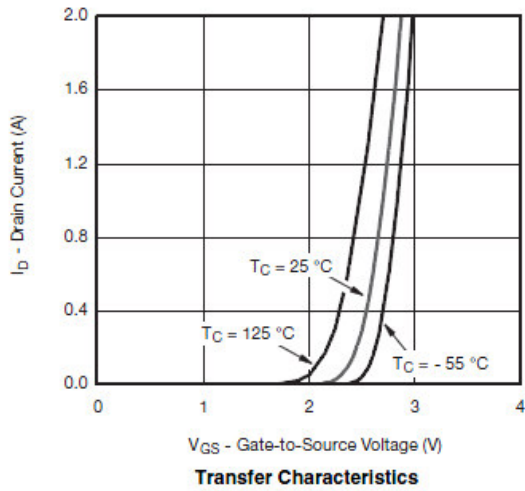
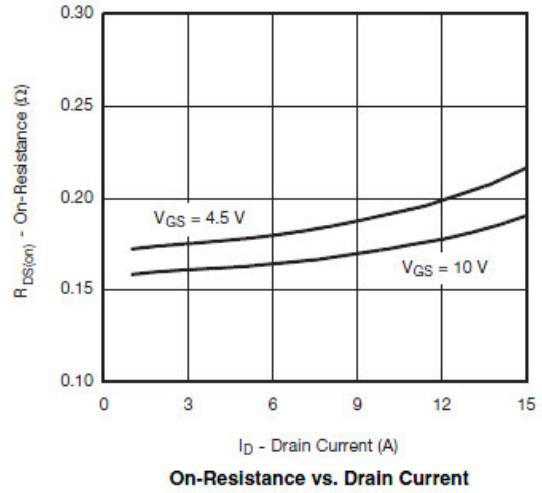
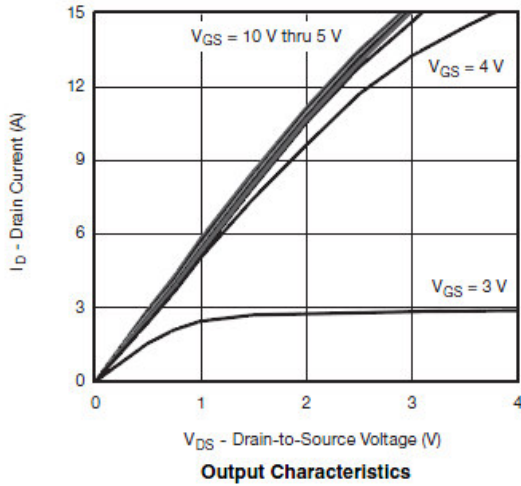


## Typical Characteristics ( N-Channel )



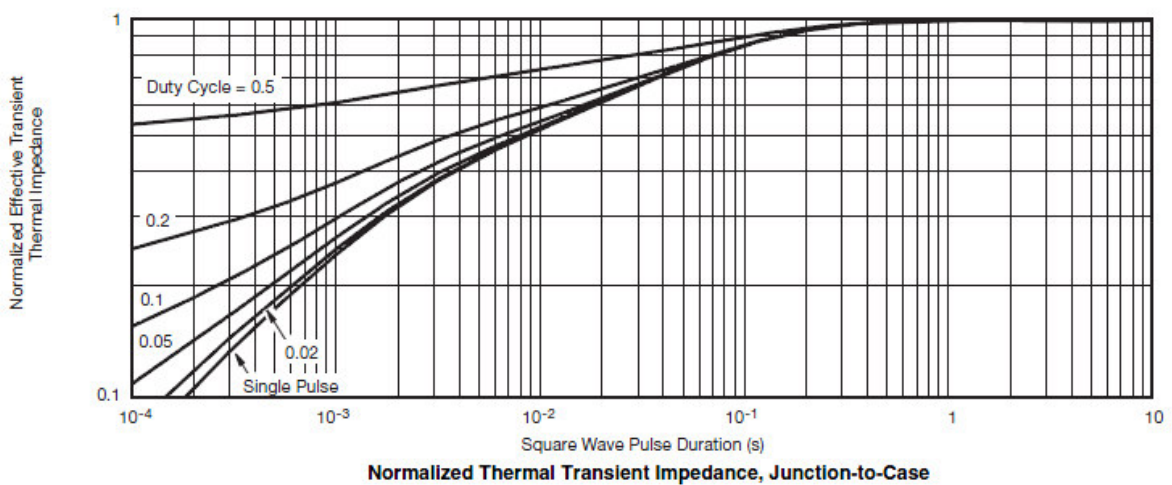
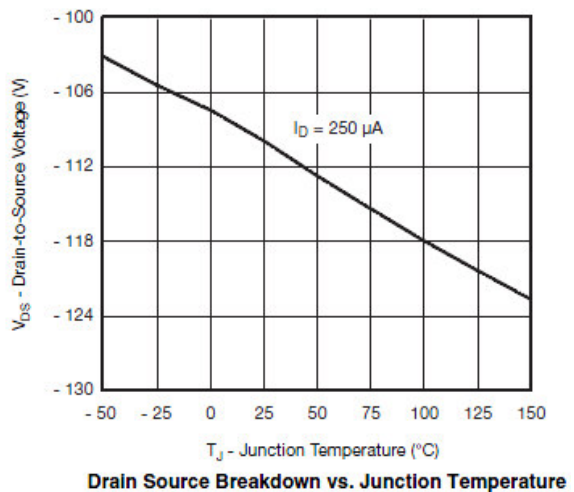
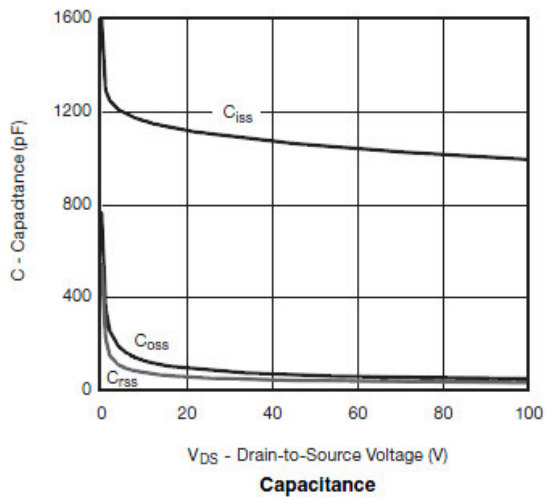
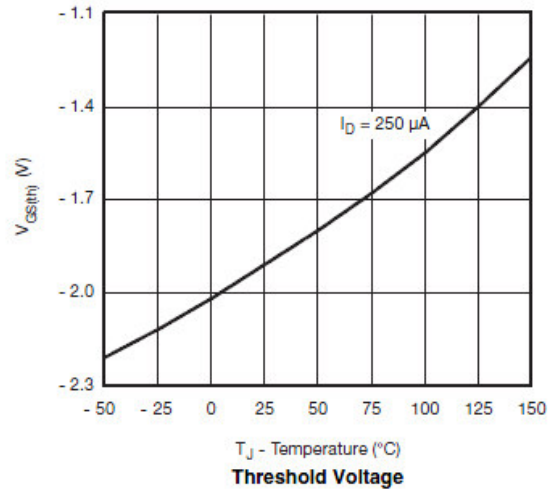
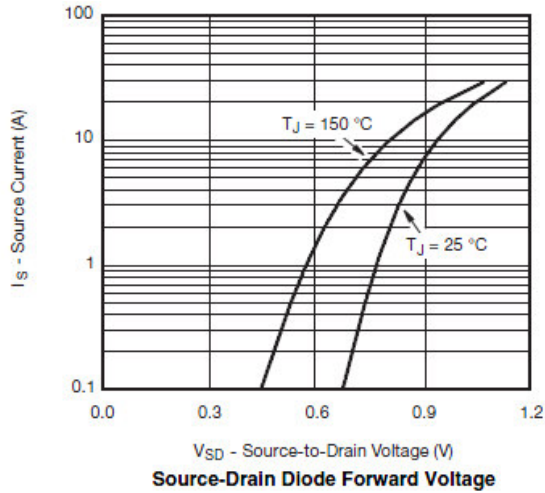


## Typical Characteristics ( P-Channel )





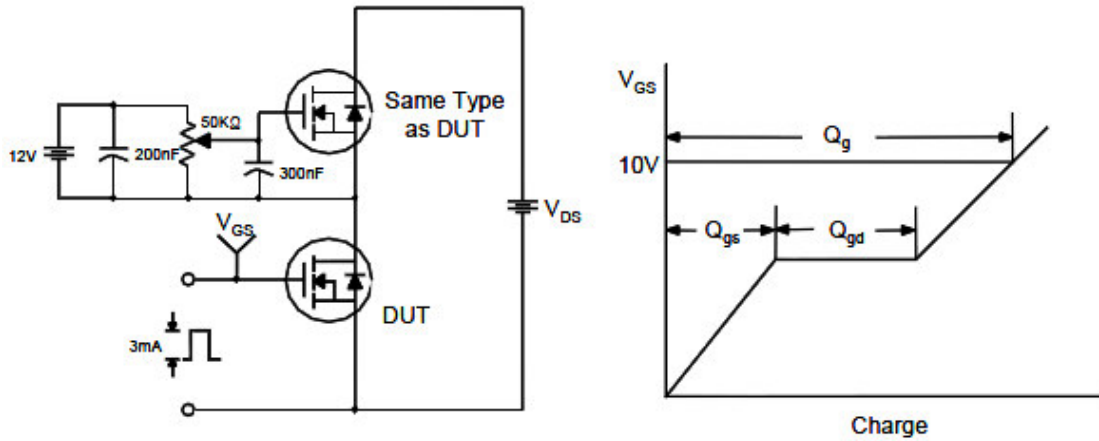
## Typical Characteristics ( P-Channel )



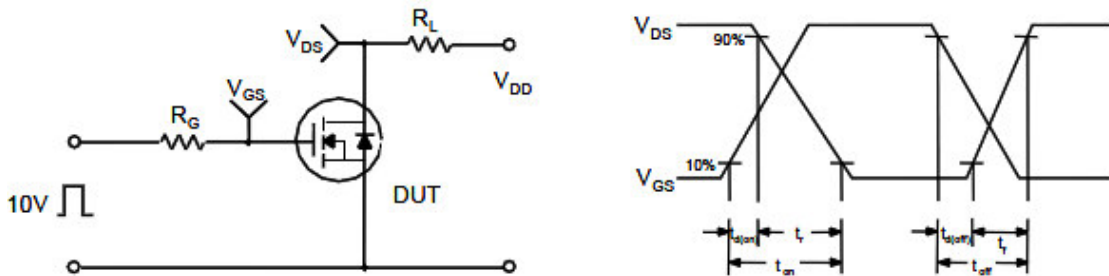


**Typical Characteristics**

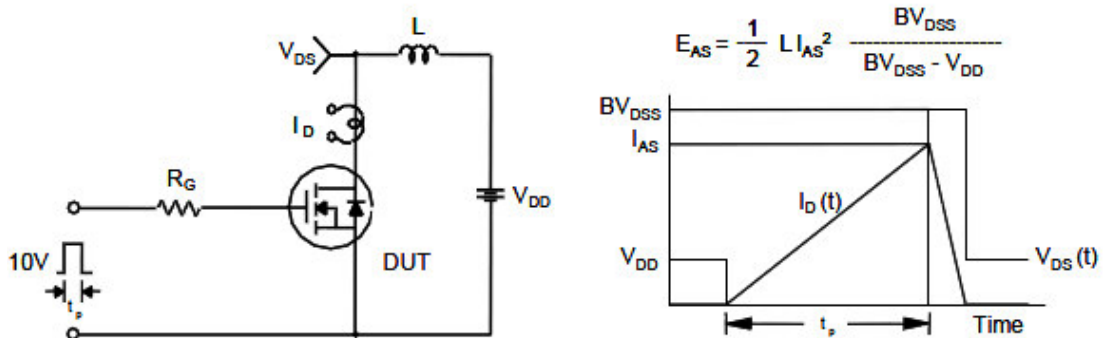
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



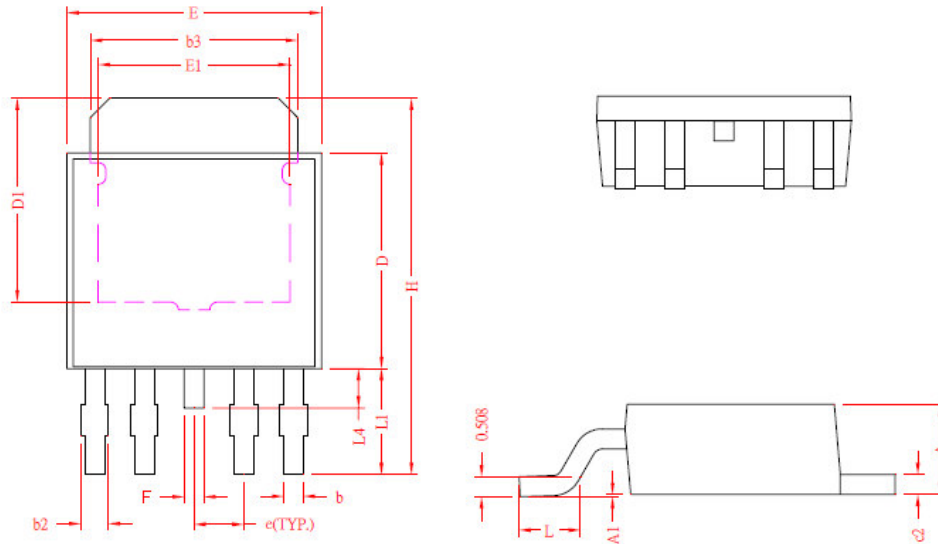
Unclamped Inductive Switching Test Circuit & Waveforms







**Package Information ( TO-252-4L )**



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.20	2.40	E	6.40	6.80
A1	0	0.15	E1	3.81	---
b	0.40	0.60	e	1.27 REF.	
b2	0.50	0.80	F	0.40	0.60
b3	5.20	5.50	H	9.40	10.20
c2	0.45	0.55	L	1.40	1.77
D	5.40	5.80	L1	2.40	3.00
D1	4.57	---	L4	0.80	1.20

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